



N-Channel 25-V (D-S) MOSFET



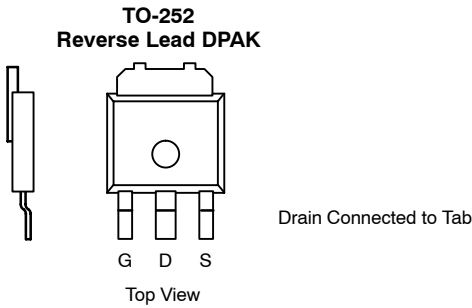
| PRODUCT SUMMARY | | | |
|---------------------|----------------------------------|------------------------------------|----------------------|
| V _{DS} (V) | r _{DS(on)} (Ω) | I _D (A) ^{a, e} | Q _g (Typ) |
| 25 | 0.0052 @ V _{GS} = 10 V | 89 | 30 nC |
| | 0.0076 @ V _{GS} = 4.5 V | 80 | |

FEATURES

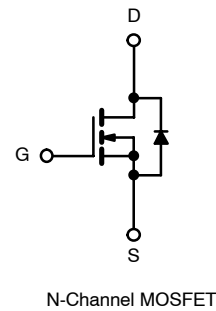
- TrenchFET® Power MOSFET
- 100% R_g Tested
- RoHS Compliant

APPLICATIONS

- DC/DC Conversion, Low-Side
 - Desktop PC
 - Notebook PC



Ordering Information:
 SUR50N025-05P—E3 (Lead (Pb)-Free)
 SUR50N025-05P-T4—E3 (Lead (Pb)-Free, alternate tape orientation)



| ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED) | | | | |
|--|------------------------|-----------------------------------|----------------------|------|
| Parameter | | Symbol | Limit | Unit |
| Drain-Source Voltage | | V _{DS} | 25 | V |
| Gate-Source Voltage | | V _{GS} | ± 20 | |
| Continuous Drain Current (T _J = 175 °C) | T _C = 25 °C | I _D | 89 ^{a, e} | A |
| | T _C = 70 °C | | 75 ^{a, e} | |
| | T _A = 25 °C | | 36 ^{b, c} | |
| | T _A = 70 °C | | 30 ^{b, c} | |
| Pulsed Drain Current | | I _{DM} | 100 | A |
| Continuous Source-Drain Diode Current | T _C = 25 °C | I _S | 55 | |
| | T _A = 25 °C | | 7.7 ^{b, c} | |
| Avalanche Current Pulse | | I _{AS} | 45 | mJ |
| Single Pulse Avalanche Energy | | E _{AS} | 101 | |
| Maximum Power Dissipation | T _C = 25 °C | P _D | 83 ^a | W |
| | T _C = 70 °C | | 58 ^a | |
| | T _A = 25 °C | | 11.5 ^{b, c} | |
| | T _A = 70 °C | | 8.0 ^{b, c} | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | -55 to 175 | °C |

| THERMAL RESISTANCE RATINGS | | | | | |
|---|--------------|-------------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 10 sec | R _{thJA} | 10 | 13 | °C/W |
| Maximum Junction-to-Case | Steady State | R _{thJC} | 1.5 | 1.8 | |

- Notes:
- Based on T_C = 25 °C.
 - Surface mounted on 1" x 1" FR4 board.
 - t = 10 sec
 - Maximum under steady state conditions is 90 °C/W.
 - Calculated based on maximum junction temperature. Package limitation current is 50 A.

| SPECIFICATIONS (T _J = 25 °C UNLESS OTHERWISE NOTED) | | | | | | |
|--|--------------------------------------|--|------|--------|--------|-------|
| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 25 | | | V |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | I _D = 250 μA | | 20 | | mV/°C |
| V _{GS(th)} Temperature Coefficient | ΔV _{GS(th)} /T _J | | | -6.0 | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | 1.4 | | 2.4 | V |
| Gate-Source Leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = ±20 V | | | ±100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 25 V, V _{GS} = 0 V | | | 1 | μA |
| | | V _{DS} = 25 V, V _{GS} = 0 V, T _J = 55 °C | | | 10 | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≥ 5 V, V _{GS} = 10 V | 50 | | | A |
| Drain-Source On-State Resistance ^a | r _{DS(on)} | V _{GS} = 10 V, I _D = 20 A | | 0.0042 | 0.0052 | Ω |
| | | V _{GS} = 4.5 V, I _D = 15 A | | 0.0062 | 0.0076 | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = 15 V, I _D = 15 A | | 65 | | S |
| Dynamic^b | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} = 12 V, V _{GS} = 0 V, f = 1 MHz | | 3600 | | pF |
| Output Capacitance | C _{oss} | | | 790 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 430 | | |
| Total Gate Charge | Q _g | V _{DS} = 12 V, V _{GS} = 10 V, I _D = 50 A | | 63 | 95 | nC |
| | | V _{DS} = 12 V, V _{GS} = 4.5 V, I _D = 50 A | | 30 | 45 | |
| Gate-Source Charge | Q _{gs} | | | 10.5 | | |
| Gate-Drain Charge | Q _{gd} | | 10.5 | | | |
| Gate Resistance | R _g | f = 1 MHz | 0.5 | 1.0 | 1.5 | Ω |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = 12 V, R _L = 0.24 Ω I _D ≅ 50 A, V _{GEN} = 4.5 V, R _g = 1 Ω | | 24 | 36 | ns |
| Rise Time | t _r | | | 13 | 20 | |
| Turn-Off Delay Time | t _{d(off)} | | | 24 | 36 | |
| Fall Time | t _f | | | 7.5 | 12 | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = 12 V, R _L = 0.24 Ω I _D ≅ 50 A, V _{GEN} = 10 V, R _g = 1 Ω | | 11 | 17 | |
| Rise Time | t _r | | | 11 | 17 | |
| Turn-Off Delay Time | t _{d(off)} | | | 29 | 44 | |
| Fall Time | t _f | | | 8 | 12 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | 55 | A |
| Pulse Diode Forward Current ^a | I _{SM} | | | | 100 | |
| Body Diode Voltage | V _{SD} | I _S = 30 A | | 0.9 | 1.5 | V |
| Body Diode Reverse Recovery Time | t _{rr} | I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C | | 34 | 51 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | | | 25 | 38 | nC |
| Reverse Recovery Fall Time | t _a | | | 17 | | ns |
| Reverse Recovery Rise Time | t _b | | | 17 | | |

Notes

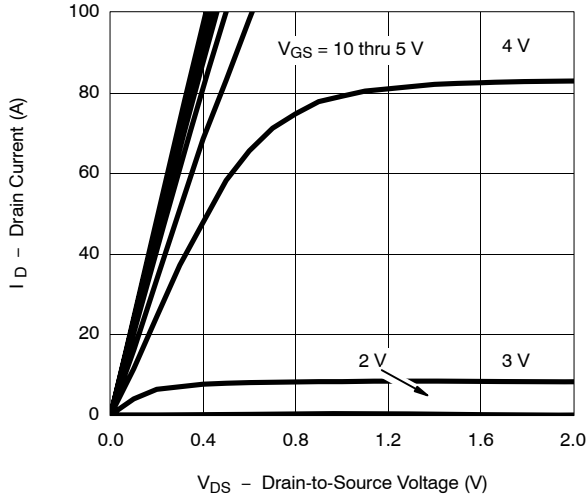
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

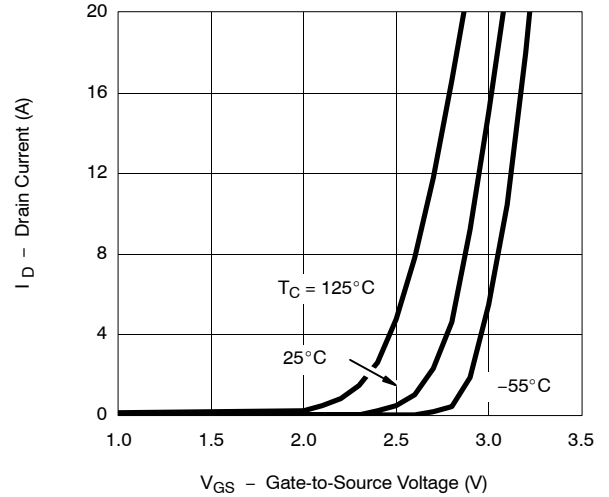


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

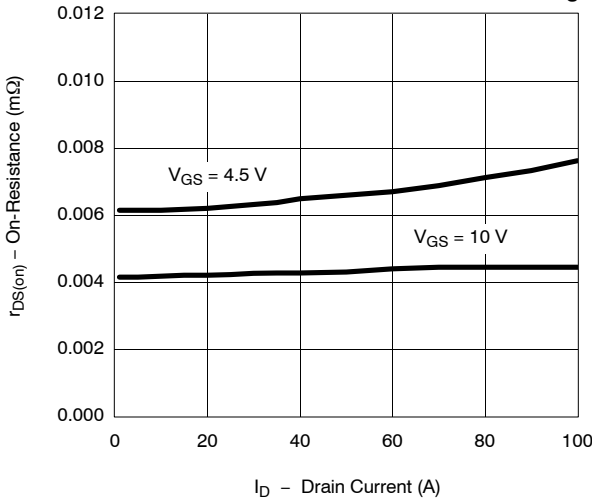
Output Characteristics



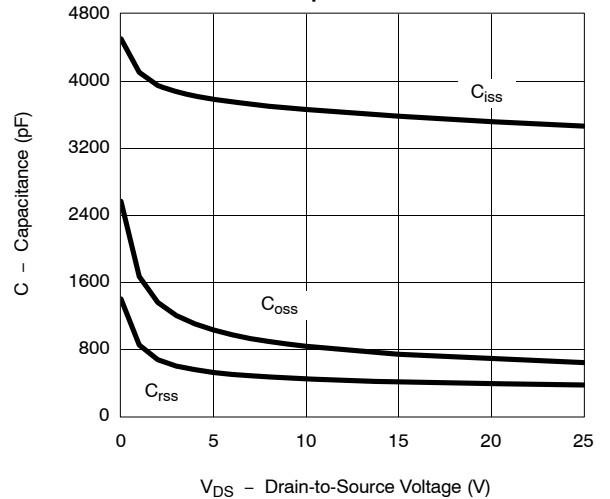
Transfer Characteristics



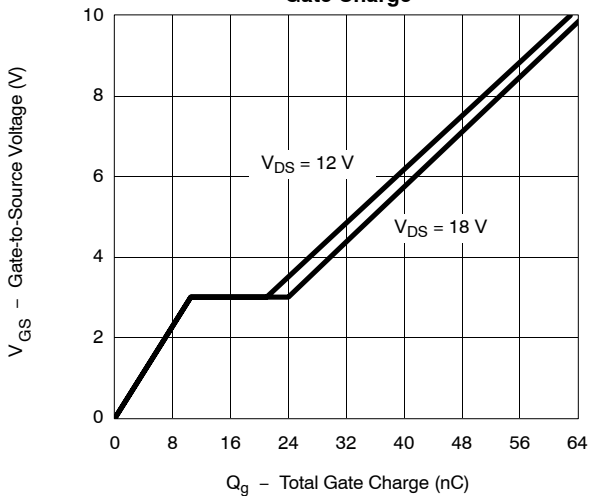
On-Resistance vs. Drain Current and Gate Voltage



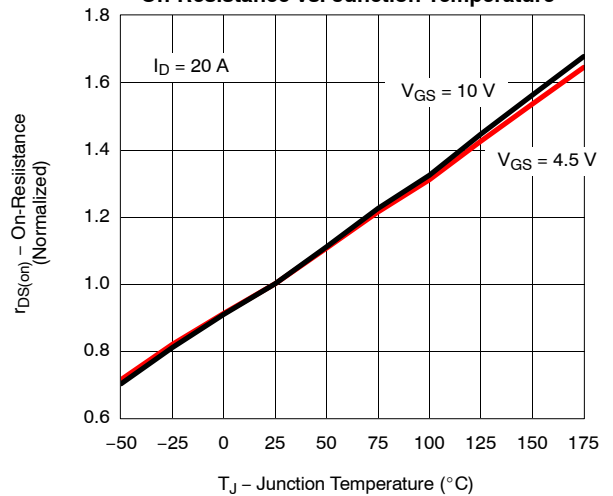
Capacitance



Gate Charge



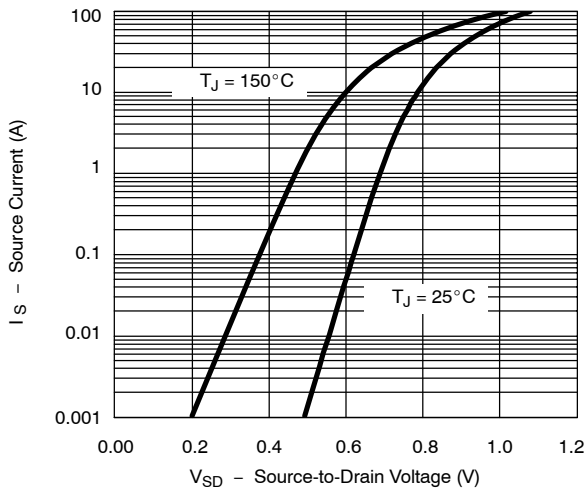
On-Resistance vs. Junction Temperature



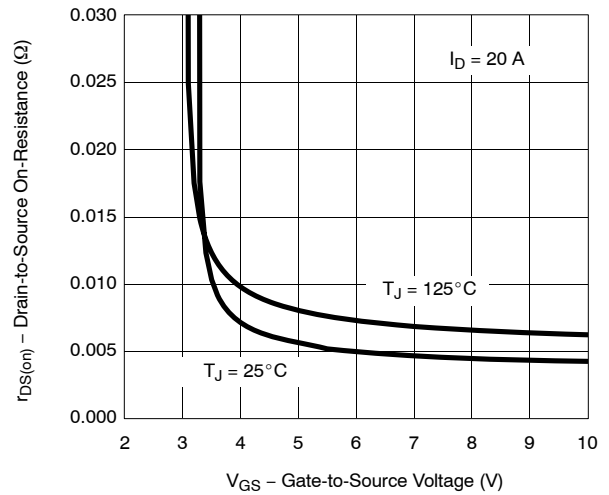


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

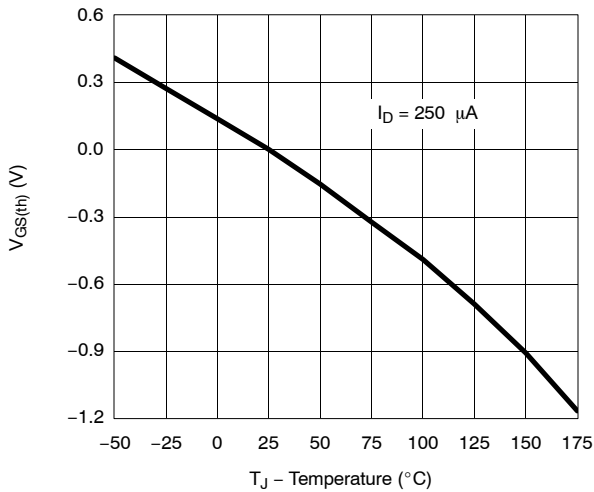
Source-Drain Diode Forward Voltage



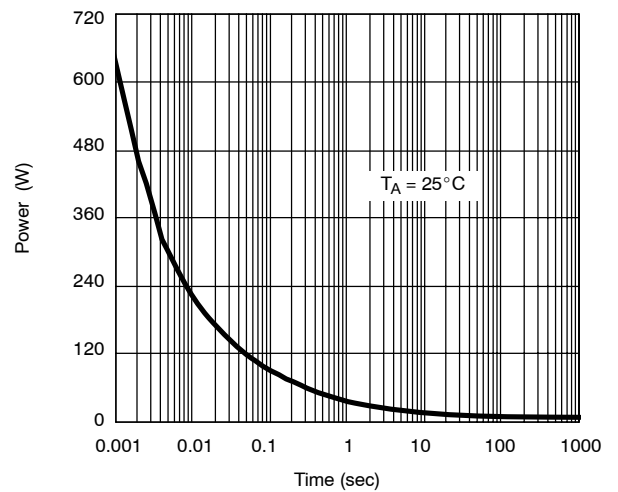
On-Resistance vs. Gate-to-Source Voltage



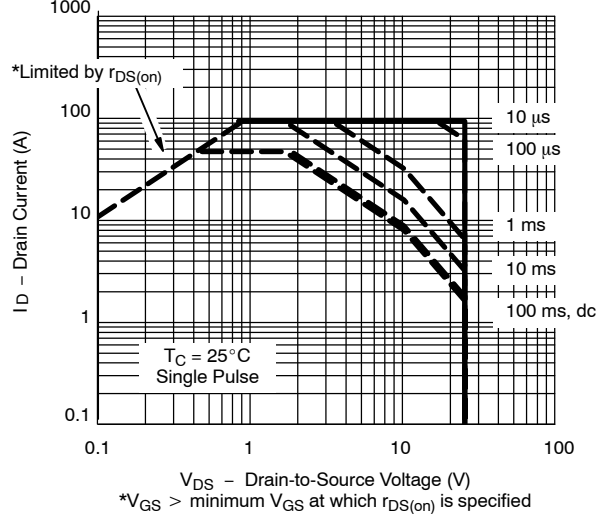
Threshold Voltage



Single Pulse Power, Junction-to-Ambient

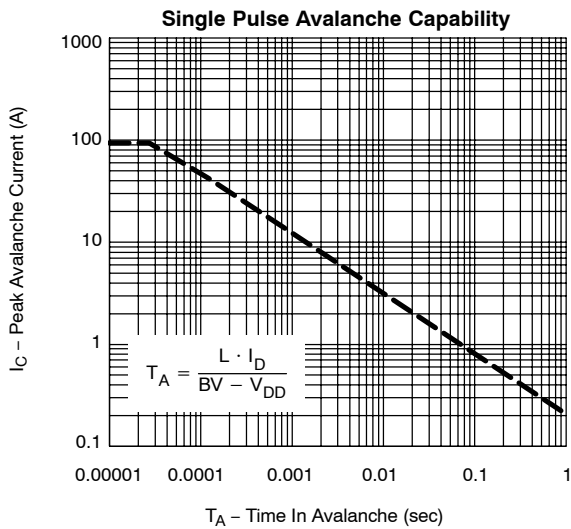
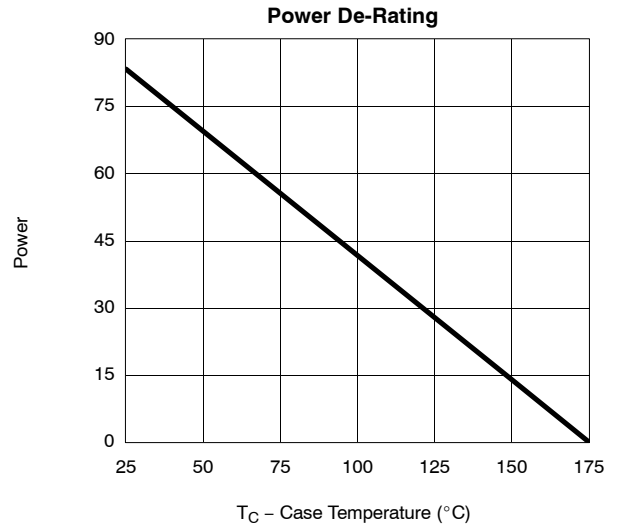
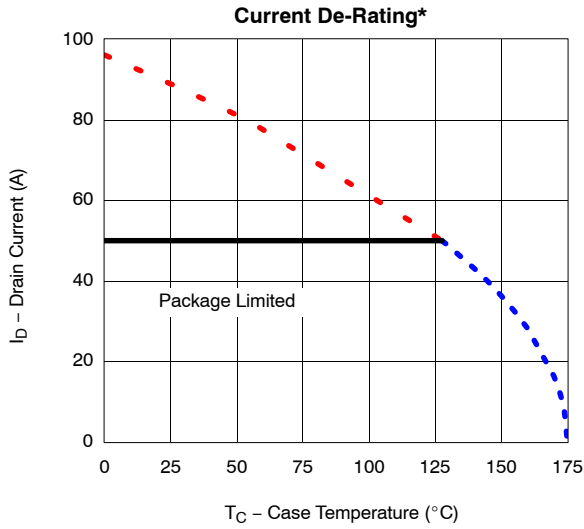


Safe Operating Area, Junction-to-Case





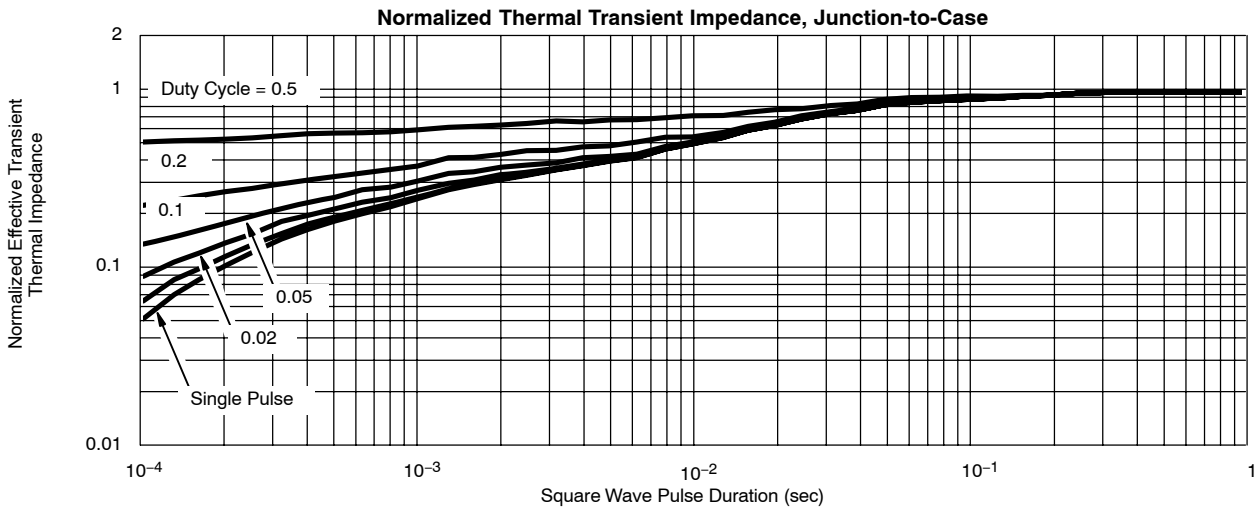
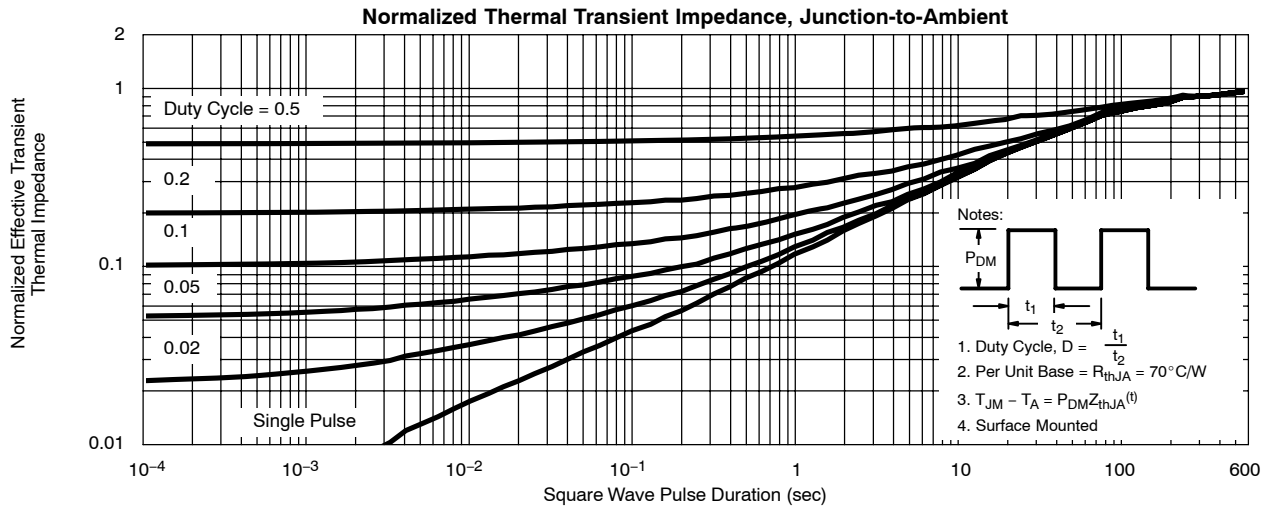
TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



*The power dissipation P_D is based on $T_{J(max)} = 175^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



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